



Material Content Data Sheet



Sales Product Name		BSZ014NE2LS5IF		Issued		1. August 2018		
MA#		MA001260042						
Package		PG-TSDSON-8-26		Weight*		35.85 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.629	1.76	1.76	17550	17550
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		101	
	non noble metal	zinc	7440-66-6	0.015	0.04		406	
	non noble metal	iron	7439-89-6	0.291	0.81		8110	
wire	non noble metal	copper	7440-50-8	11.804	32.93	33.79	329298	337915
	non noble metal	copper	7440-50-8	0.013	0.04	0.04	354	354
	encapsulation	organic material	carbon black	1333-86-4	0.035	0.10		977
plastics	plastics	epoxy resin	-	1.805	5.03		50340	
	inorganic material	silicondioxide	60676-86-0	15.680	43.74	48.87	437416	488733
	leadfinish	non noble metal	tin	7440-31-5	0.395	1.10	1.10	11027
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	567	567
solder	non noble metal	tin	7440-31-5	0.019	0.05		523	
	noble metal	silver	7440-22-4	0.023	0.07		653	
	non noble metal	lead	7439-92-1	0.895	2.50	2.62	24955	26131
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		35	
	non noble metal	zinc	7440-66-6	0.005	0.01		141	
	non noble metal	iron	7439-89-6	0.101	0.28		2825	
	non noble metal	copper	7440-50-8	4.112	11.47	11.76	114722	117723
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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